

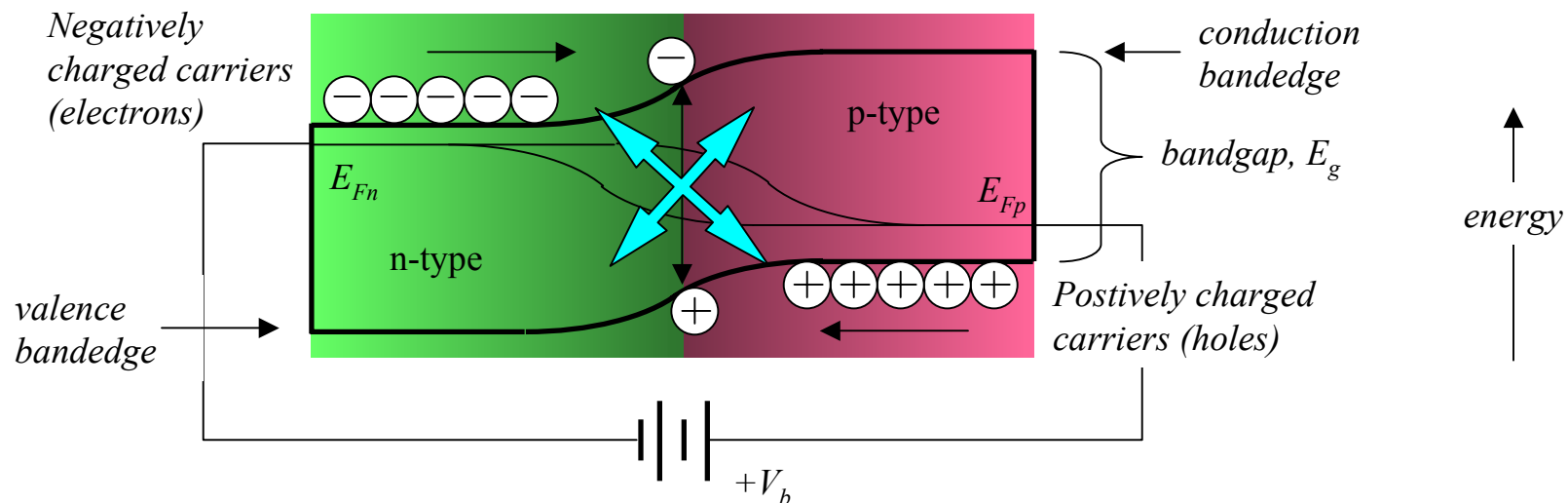


## *Progress and Future Direction of LED Technology*

**Mike Krames, Lumileds Lighting**

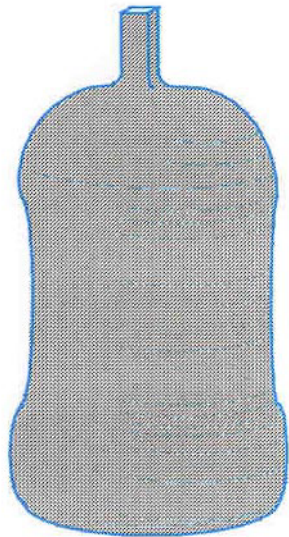
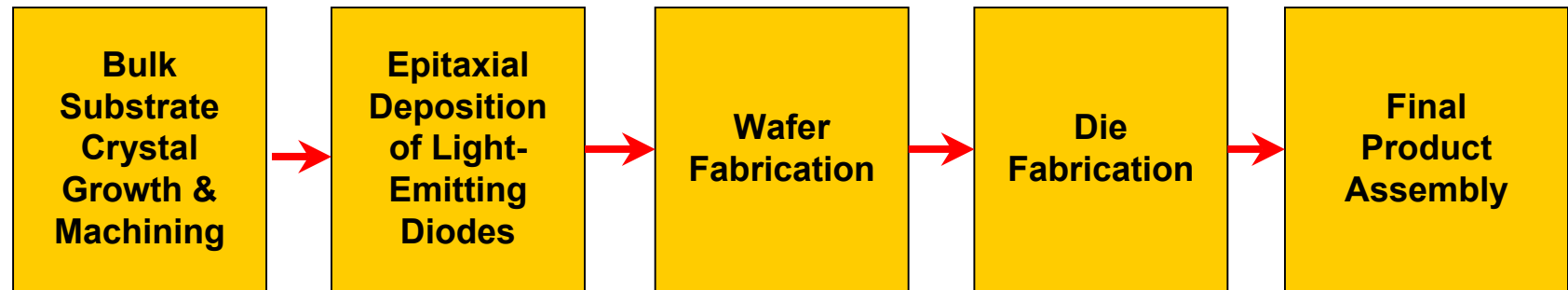
**SSL Workshop  
13 Nov, 2003  
Arlington, VA**

# What is a light-emitting diode?



- **Crystalline semiconductor atomic arrangement determines bandgap**
  - Specifies optical properties
- **Impurity doping provides p- and n-type regions**
- **At forward bias, injected electrons and holes recombine**
- **Energy may be released as radiative (light) or non-radiative (heat)**
- **Fundamentally non-destructive process**

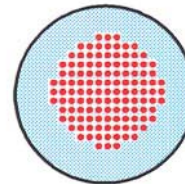
# LED Fabrication



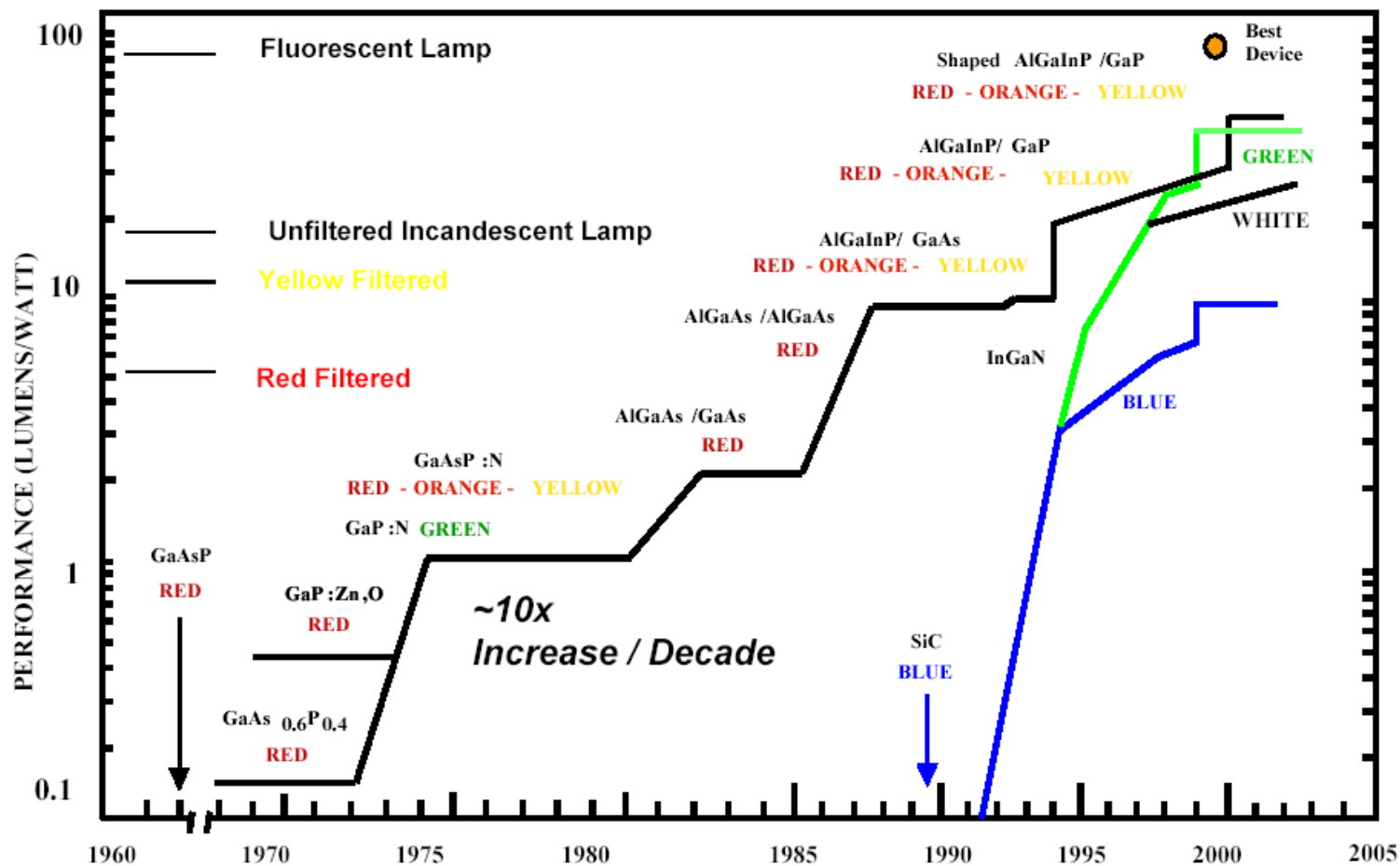
e.g., GaAs,  
 $\text{Al}_2\text{O}_3$ , SiC



e.g., metal-organic  
chemical vapor  
deposition  
(MOCVD)



# Evolution of LED Efficiency



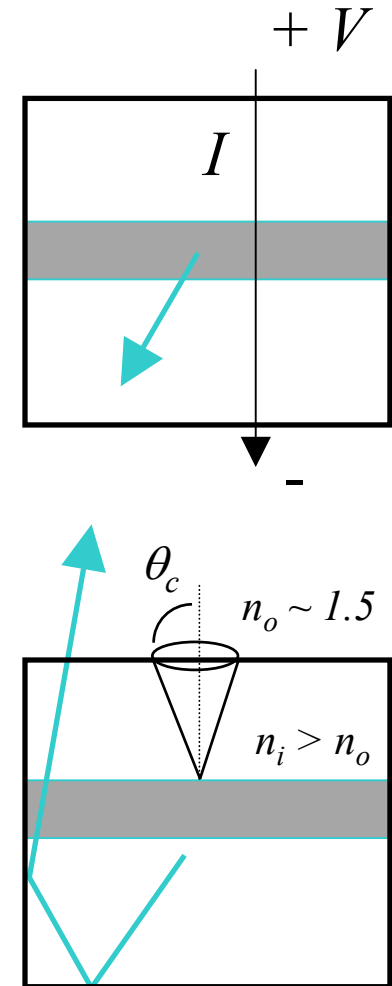
# External Quantum Efficiency = Internal QE x Extraction Efficiency

## Internal Quantum Efficiency, $\eta_{int}$ :

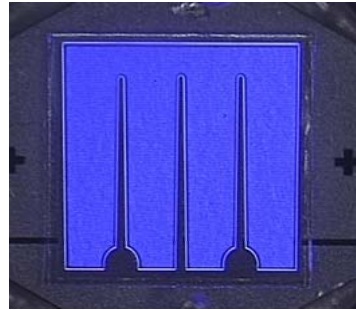
- material quality (defects, impurities)
- epitaxial layer structure and composition
- characteristics of material system
  - e.g. electronic bandstructure

## Extraction Efficiency, $C_{ext}$ :

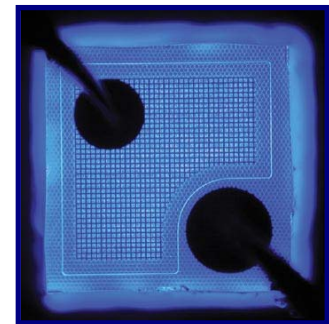
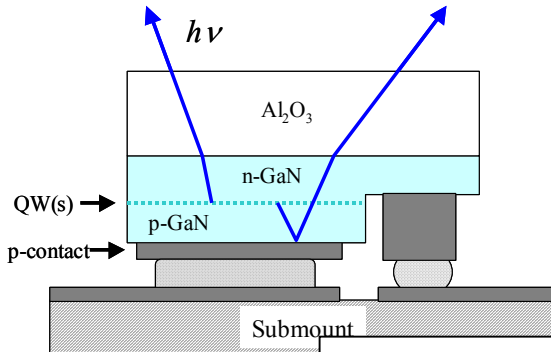
- optical characteristics of chip
  - refractive index,  $n_i > n_o$  (Snell's law)
  - “escape cone”  $\sim \frac{1}{4} (n_o/n_i)^2$  (5-10% / surface)
- internal absorption (losses) inside chip
- geometry of chip (thick- vs. thin-film; shape)
- degree of scattering



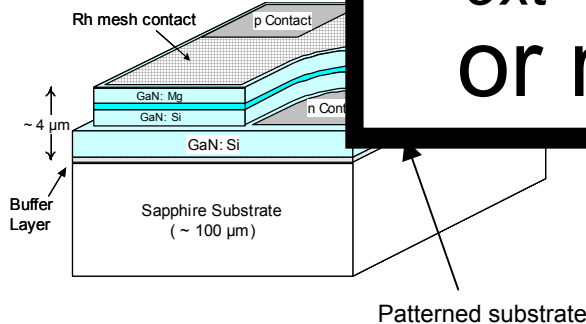
# High Extraction Efficiency Structures



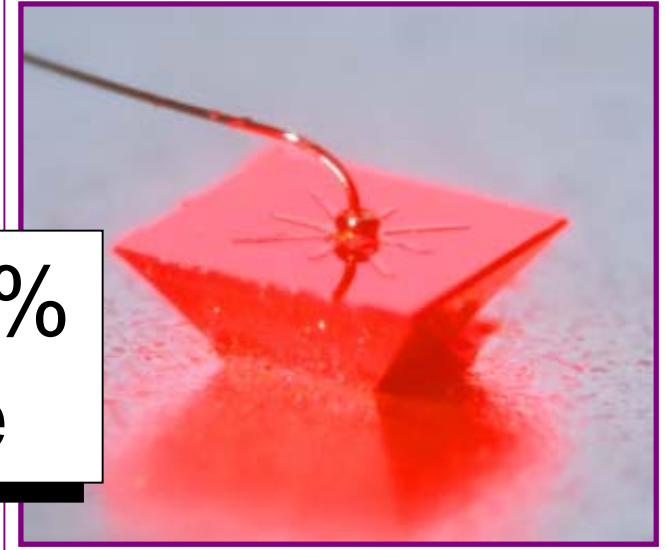
LUMILEDS™  
LIGHT FROM SILICON VALLEY



NICHIA



$C_{ext} \sim 50\%$   
or more

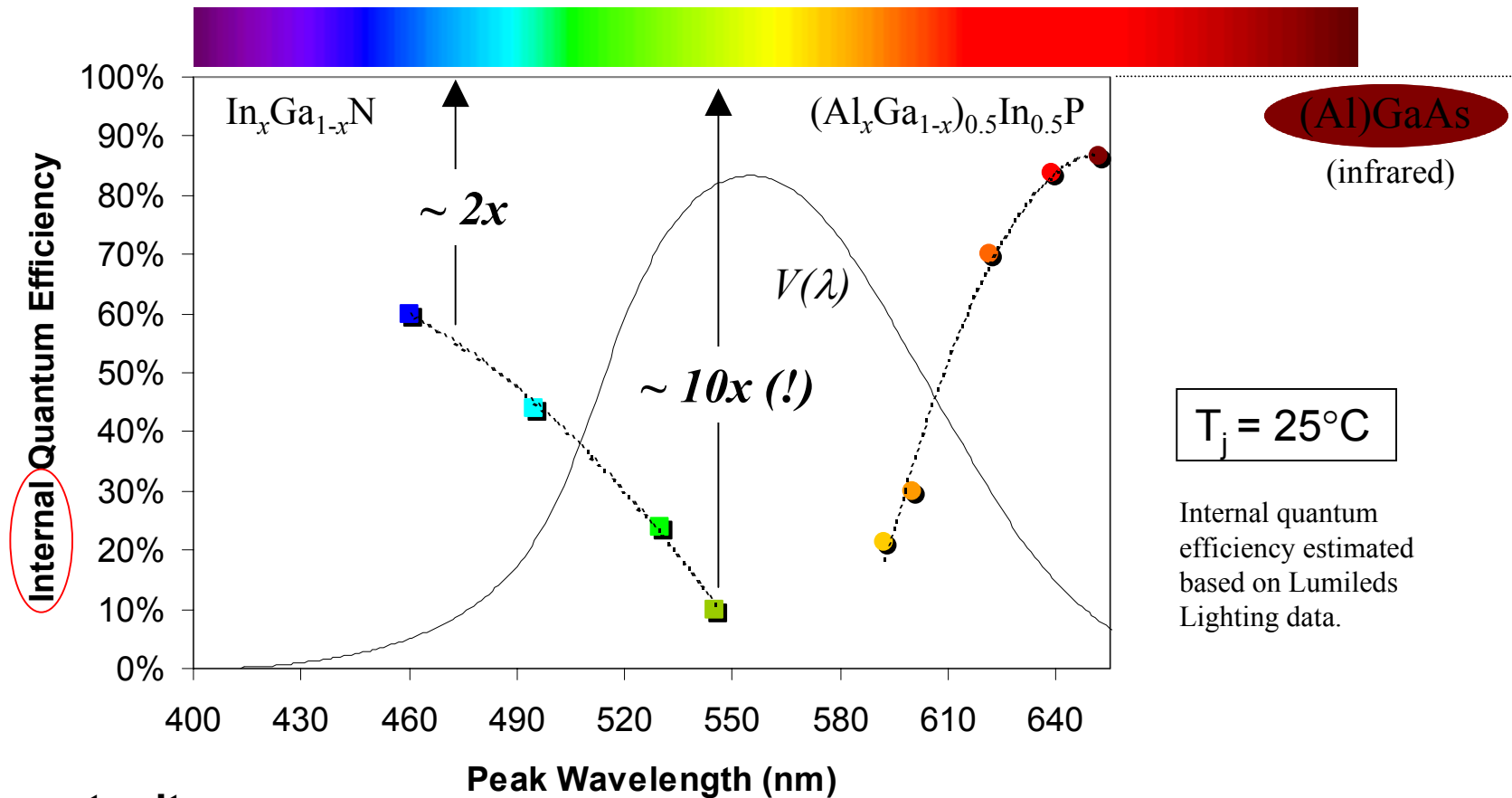


LUMILEDS™  
LIGHT FROM SILICON VALLEY

Many options:

- Flipchip with reflective electrodes
- Conventional with transparent electrode & scattering features
- Thin-film with reflective intermetallic & scattering features
- Thick-film with die shaping

# State of Art: Internal QE

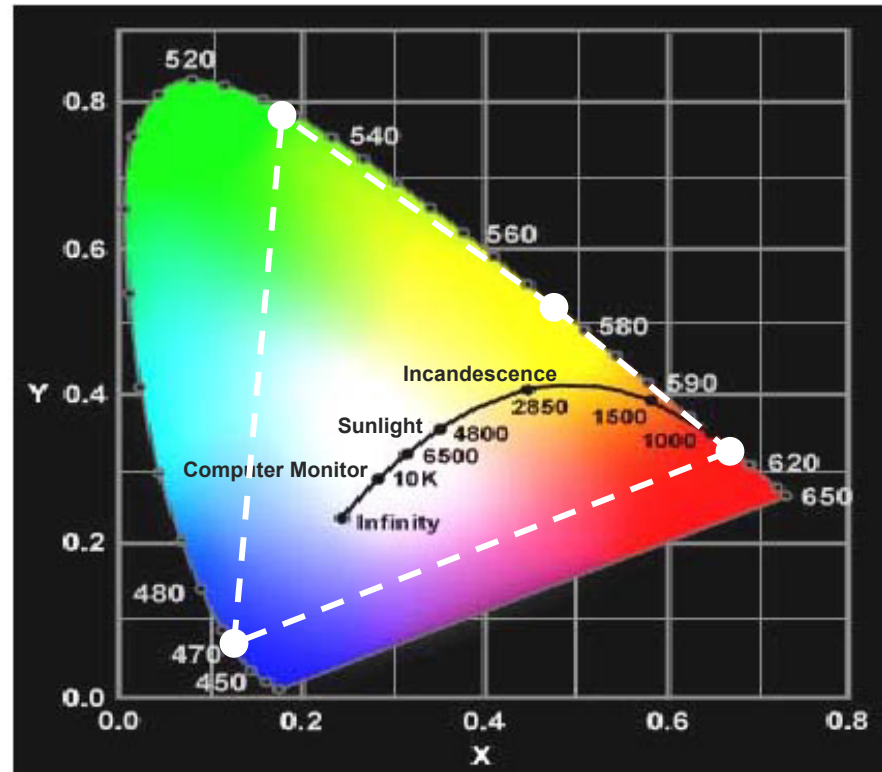
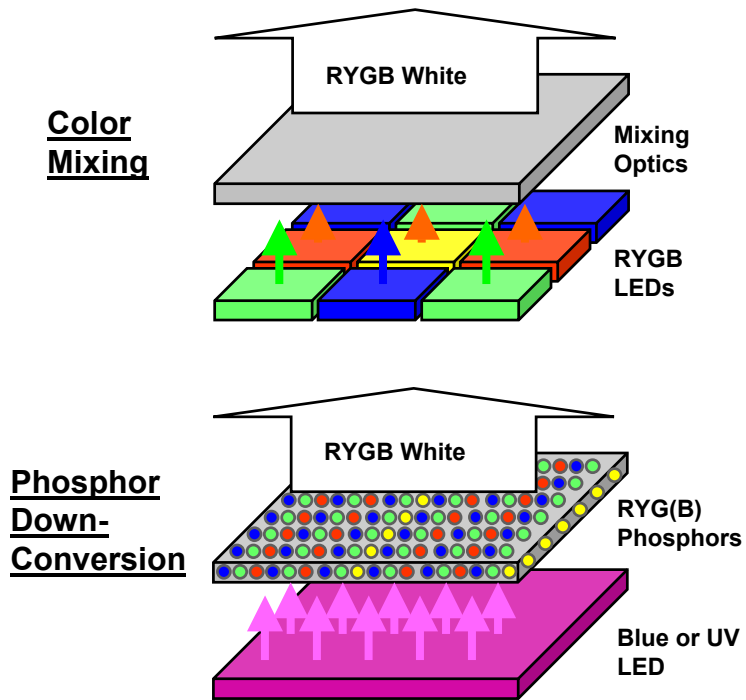


## Opportunity:

- Extraction efficiency: 2x increase max (theoretical limit)
- Internal quantum efficiency: up to 10x (!) at peak of eye sensitivity
- Example: At 100%  $\eta_{int}$  today's green LEDs would exceed 250 lm/W



# Making White



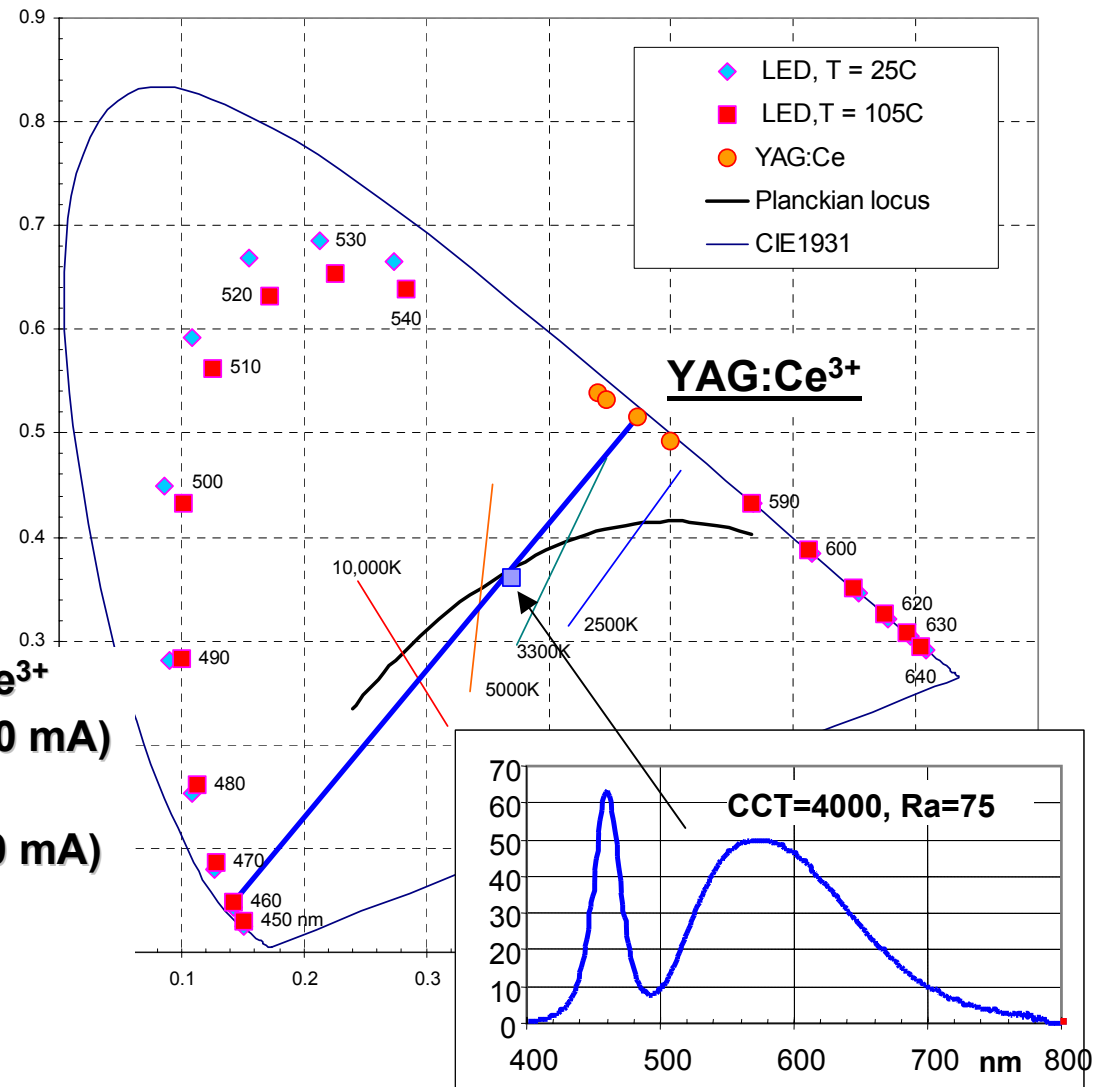
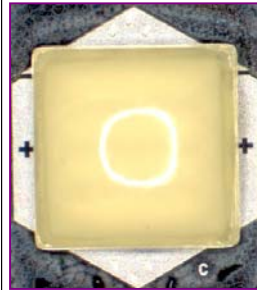
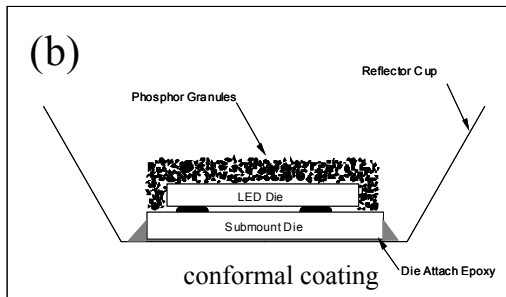
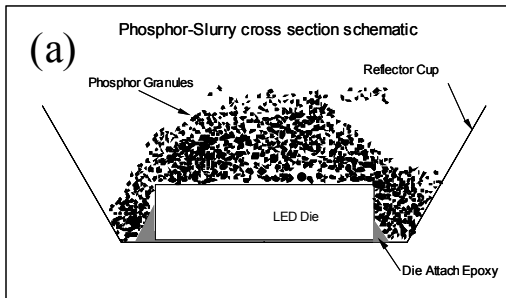
## Issues:

- **Phosphor conversion**
  - Quantum deficit, optical losses, new materials issues
- **Color mixing**
  - Optical losses (mixing), color uniformity, color control circuits

Images courtesy Jeff Tsao  
(Sandia National Labs).



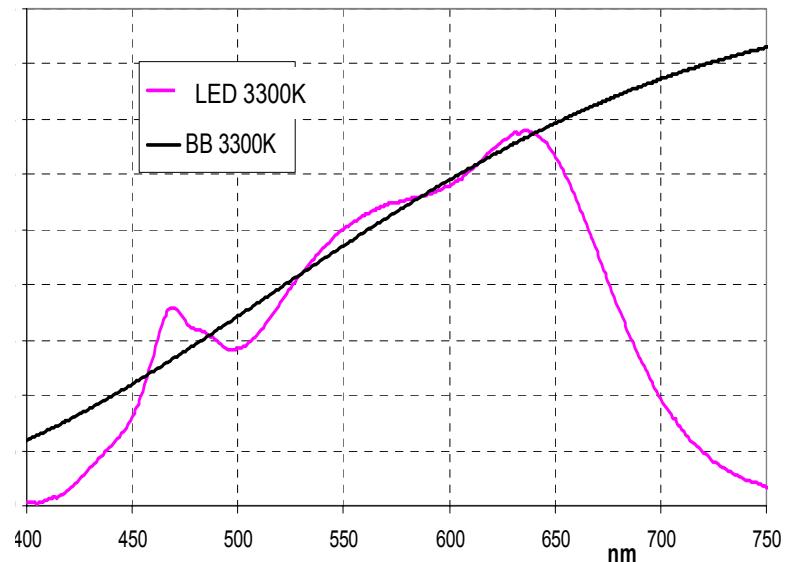
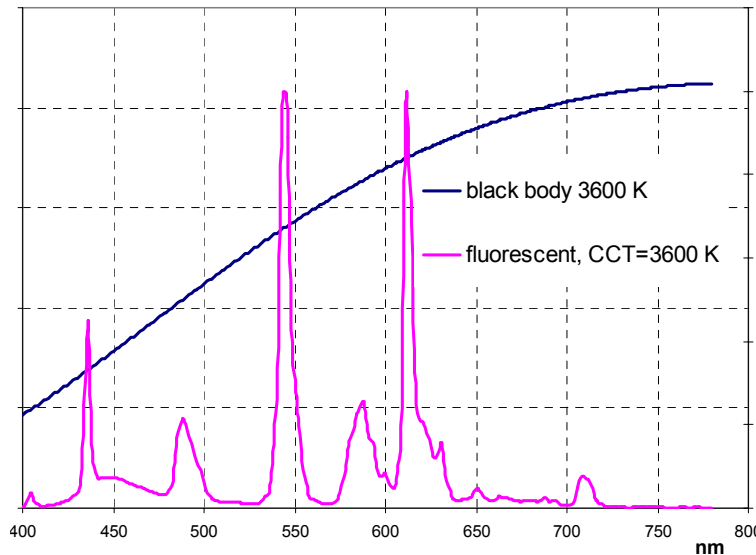
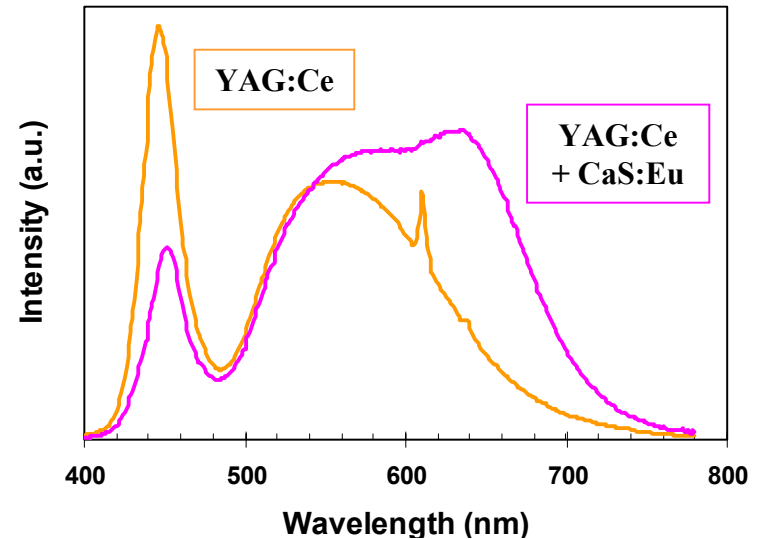
# Phosphor-based White LEDs I



- **Predominant: blue LED + YAG:Ce<sup>3+</sup>**
- **Production typical: ~ 30 lm/W (350 mA)**
  - Conversion efficiency ~ 60%
- **Laboratory results: > 60 lm/W (20 mA)**
- **Limitations:**
  - ~ 4000-8000K
  - Low CRI: ~75 (max.)

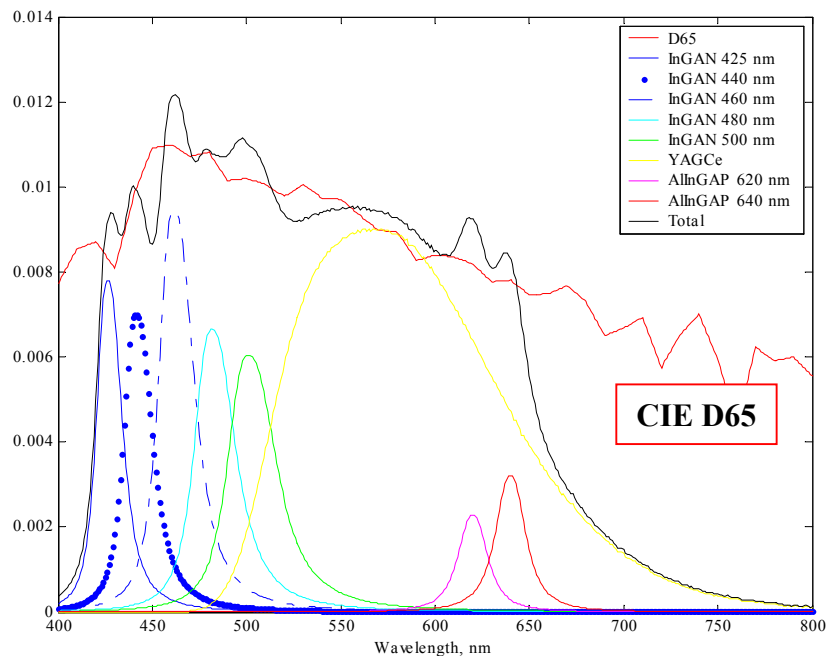
# Phosphor-based LEDs for Illumination

- Recent product release
- From YAG:Ce to YAG:Ce + CaS:Eu
  - CRI: ~75 ~90
  - CCT: ~6000K ~3200K
  - $\eta_L$ : ~30 lm/W ~20 lm/W
- Excellent match to blackbody radiation
- Challenge: optical losses
  - Conversion efficiency ~ 40%

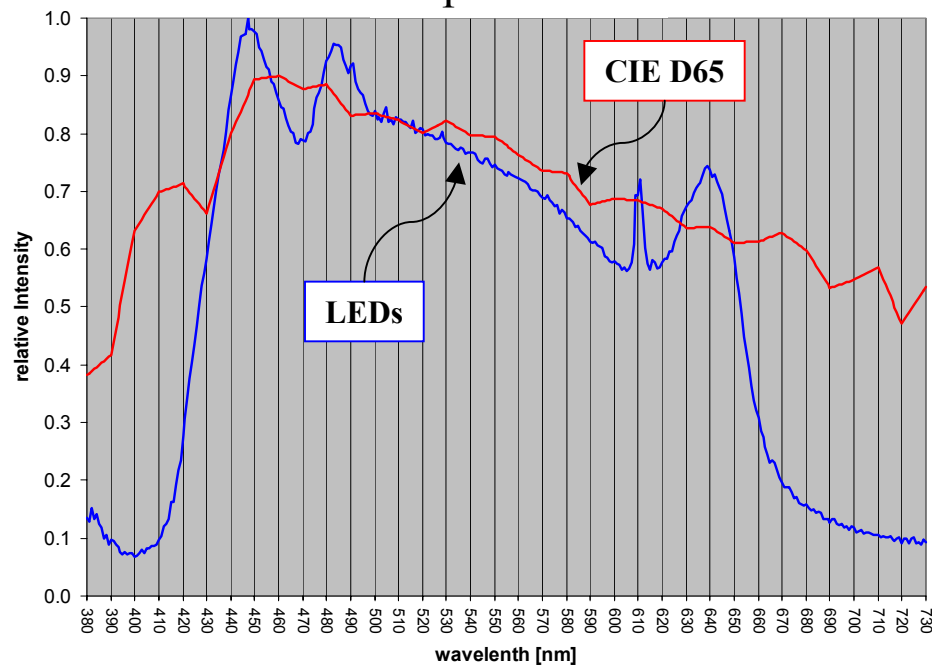


# High-Fidelity, Tuneable White

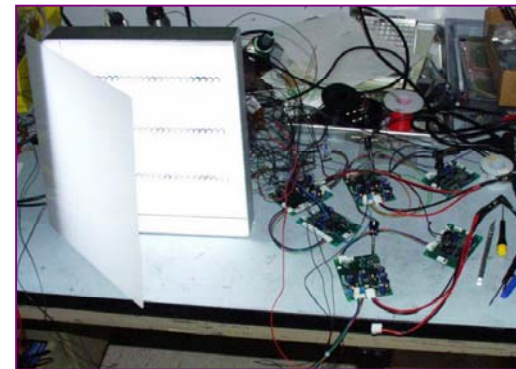
Simulation



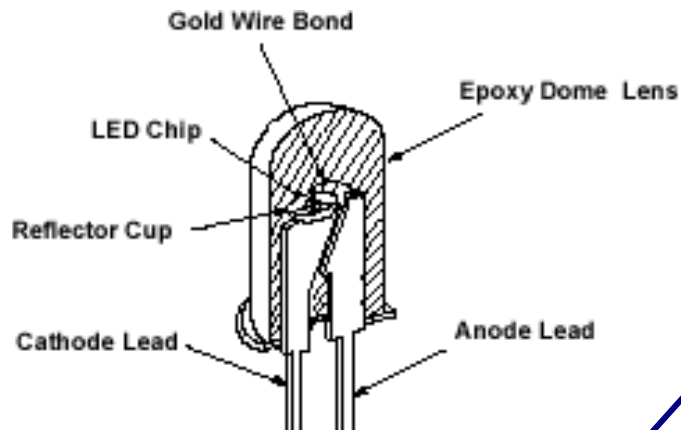
Experimental



- **Prototype:** to match D65 from ~420 to ~650 nm
- **Mix of InGaN, AlGaInP and phosphor-based LEDs**
- **Color rendering, CRI = 96 ( $R_{a,14} = 94$ )**
- **RGB (3-line): CRI < 90**



# Packaging Technology

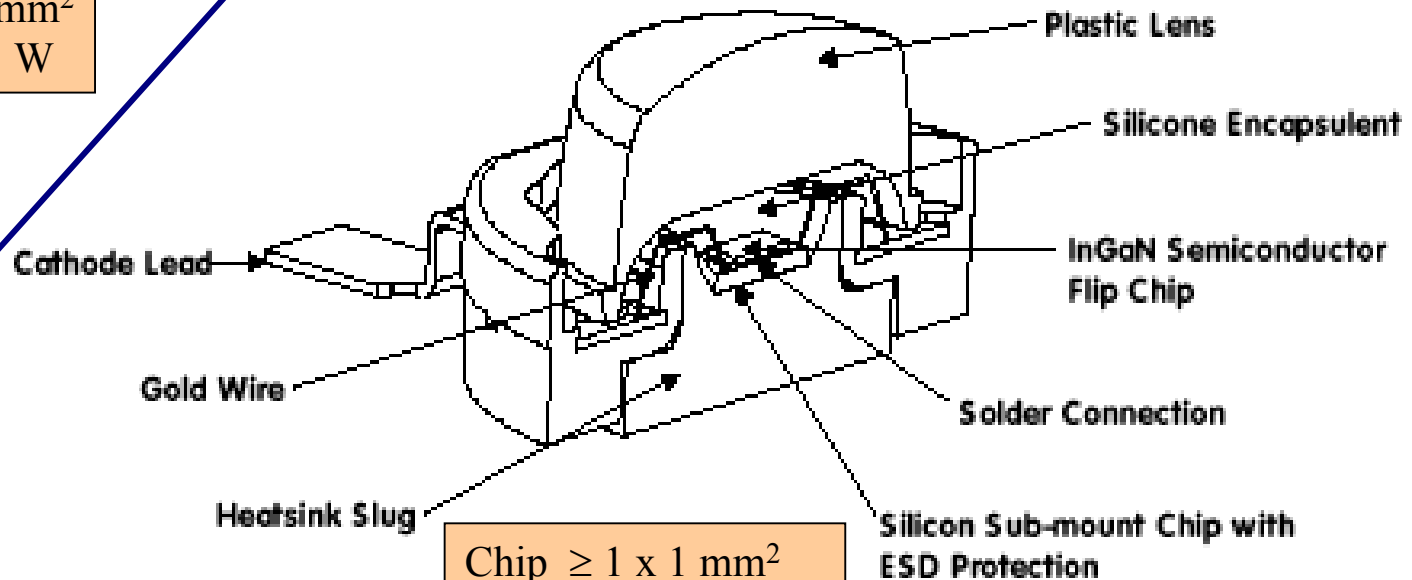


Chip  $\leq 0.35 \times 0.35 \text{ mm}^2$   
Input power  $< \sim 0.1 \text{ W}$

5mm LED

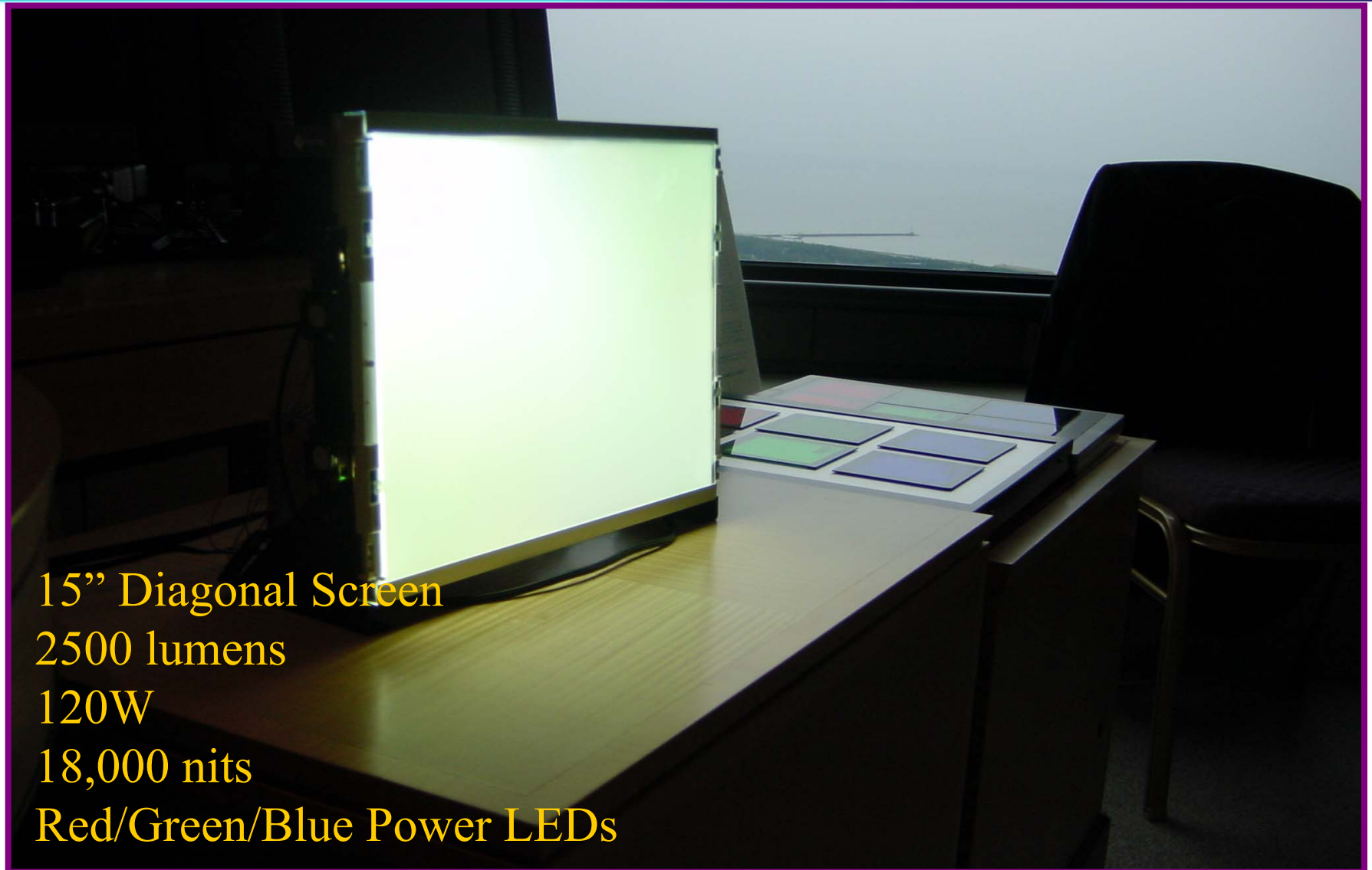


LUXEON  
A NEW WORLD OF LIGHT



Chip  $\geq 1 \times 1 \text{ mm}^2$   
Input power  $\sim 1\text{-}5 \text{ W}$

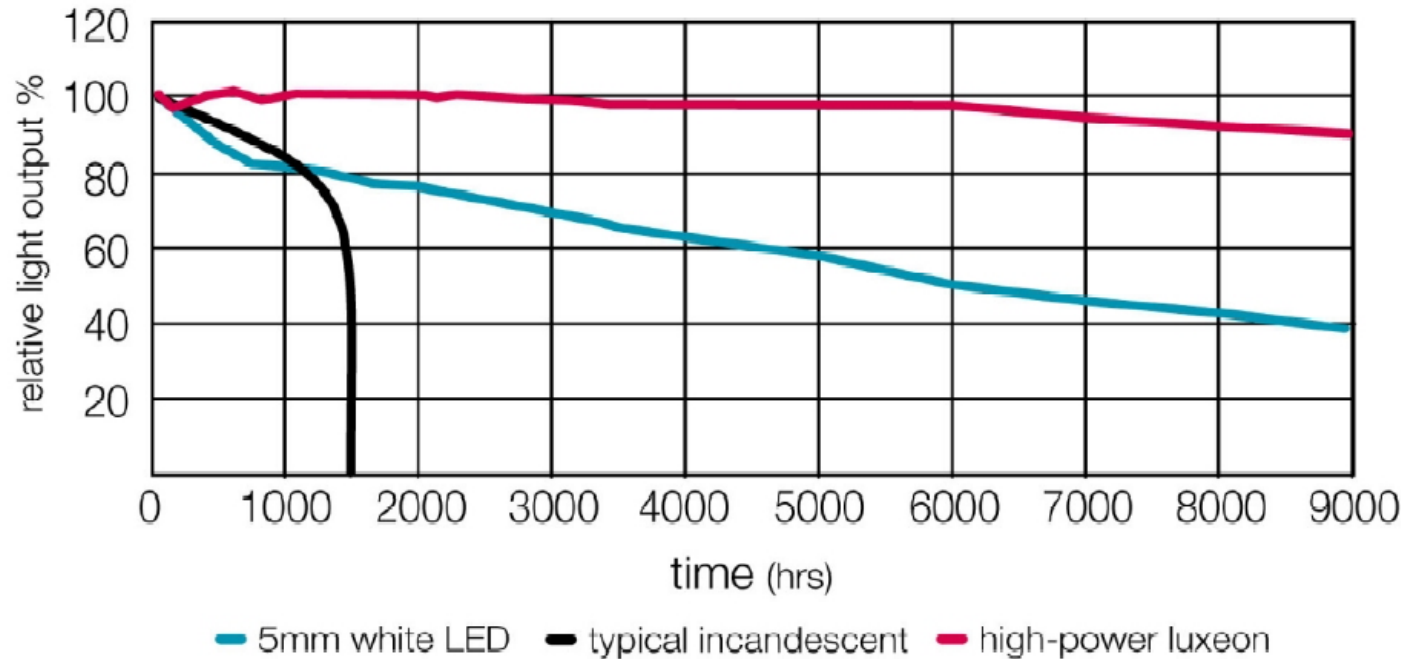
# Backlighting and Light Tile Concepts



15" Diagonal Screen  
2500 lumens  
120W  
18,000 nits  
Red/Green/Blue Power LEDs

# Reliability (1 Watt vs. “5 mm”)

## White Light Lumen Maintenance



- **Standard 5 mm lamp LEDs degrade**
  - Epoxy yellowing
- **Luxeon 1 W (1x1 mm<sup>2</sup> chip; 350 mA)**
  - 50 khrs to 70% light output ( $T_j < 90^{\circ}\text{C}$ )



# Higher Power LEDs (5 W)



**15 W**  
110 lm/bulb  
7 lm/W  
Incandescent



**4 W**  
145 lm/bulb  
36 lm/W  
Fluorescent



**Luxeon™ 5W**  
**150 lm/bulb**  
30 lm/W  
2x2 mm<sup>2</sup> chip

- **> 10 W: new packages under development**



# Status vs. OIDA Roadmap



Product performance

		2002	2003	2007	2012	2020
<b>Luminous Efficiency</b>	lm/W	25	30 (20)	75	150	200
<b>Lifetime</b>	khrs	20	50*	20	100	100
<b>Flux</b>	lm	25	150 (24*)	200	1000	1500
<b>Cost (Street Price)</b>	\$/klm	\$200	\$160*	\$20	\$5	\$2
<b>Color Rendering</b>	Ra(8)	75	75 (90)	80	80	80
<b>Markets Penetrated</b>	-	low flux	low flux	incandescent	fluorescent	all
Source: OIDA 2002a			*1 W LEDs			

- **Outlook to 2007**

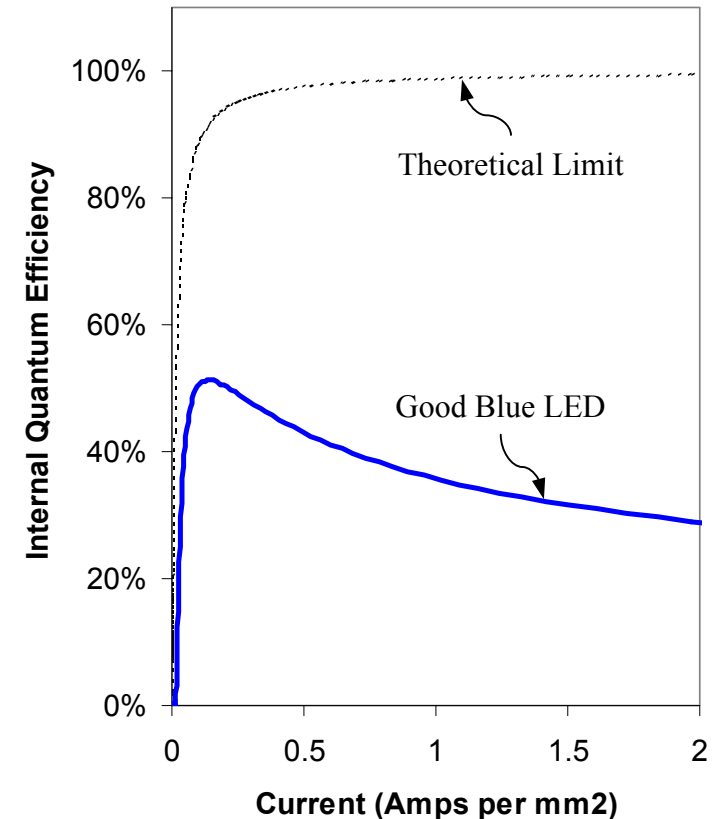
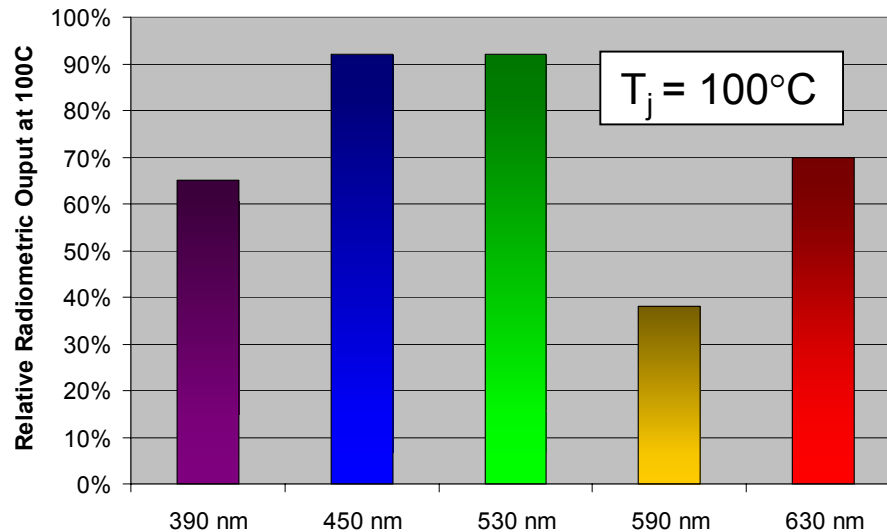
- Efficiency → 2-4x
- Cost → 8x (!)



Input power density → > 3x

# Increasing Power Density

- **Standard power LED**
  - 1 x 1 mm<sup>2</sup> chip: ~ 350 mA drive ea.
- **New power LED (Luxeon III)**
  - 1 x 1 mm<sup>2</sup> chip: up to ~ 1000 mA drive ea.
  - Typical: 80 lm white (high CCT)
  - ~ 21 lm/W ( $T_j = 25^\circ\text{C}$ )
  - Lifetime: 20khrs (50% brightness)
- **Increasing power density costs efficiency** →
- **Increasing temperature costs efficiency**



# The Future in Performance

- **Largest cost reduction lever is ever more lm per mm<sup>2</sup>**
  - Requires increased power density
  - Must maintain high efficiency (energy savings)
    - Better material quality (internal quantum efficiency)
    - Improved device structures (high current, high temperature)
    - High conversion/mixing efficiency (to white)
    - Thermal management
    - Robust packaging materials (high flux, high temperature)

# Summary I

- **Sustained rapid progress into 21<sup>st</sup> century**
  - **Phosphor-based White**
    - Single-phosphor (CRI~75)
      - Production LEDs available with ~ 30 lm/W
      - Laboratory results > 60 lm/W
      - 1000-lumen prototypes demonstrated
    - Multi-phosphor
      - Color rendering: CRI ~ 90 at 20 lm/W
  - **Direct-based White**
    - Demonstration high-fidelity white (D65 match, Ra>90)
    - Huge opportunity for improvement in green
    - Issues with temperature for AlGaInP
      - InGaN red?

# Summary II

- **Challenges ahead**
  - Decreased \$/klm requires substantial increase in lumens per mm<sup>2</sup> of LED material
    - Better materials = largest gains
  - Improved manufacturing technology for lower costs
    - e.g., better III-nitride epitaxy using *in situ* tools
  - For substantial energy savings, must have technological entry point to large base of illumination market
    - Socket compatible solutions
    - How do we mate chip/level-1 platform to existing sockets?
      - Integrated thermal management
      - Imbedded circuitry for drive conditioning & color control

# LEDs vs. Conventional Sources

